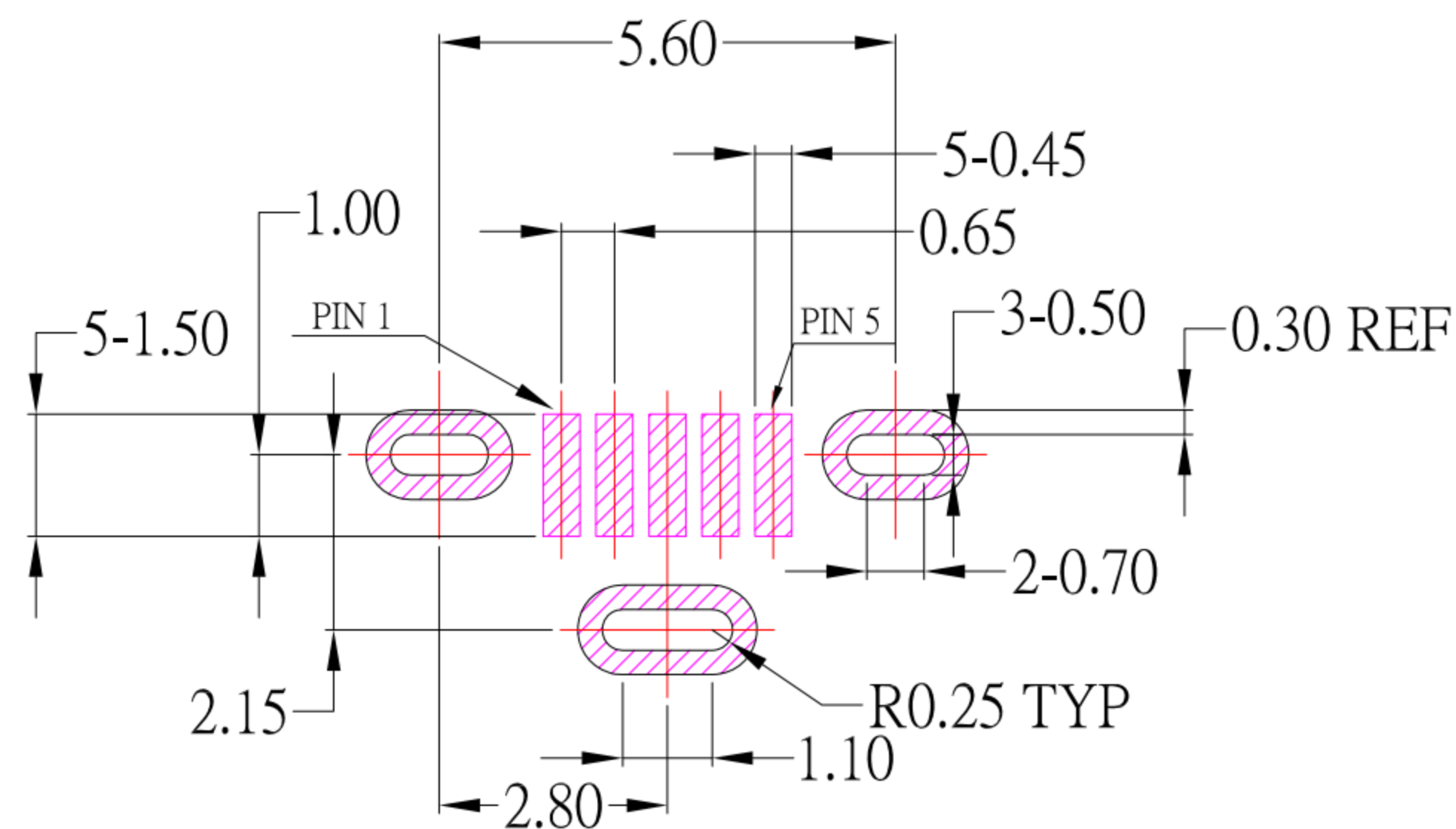
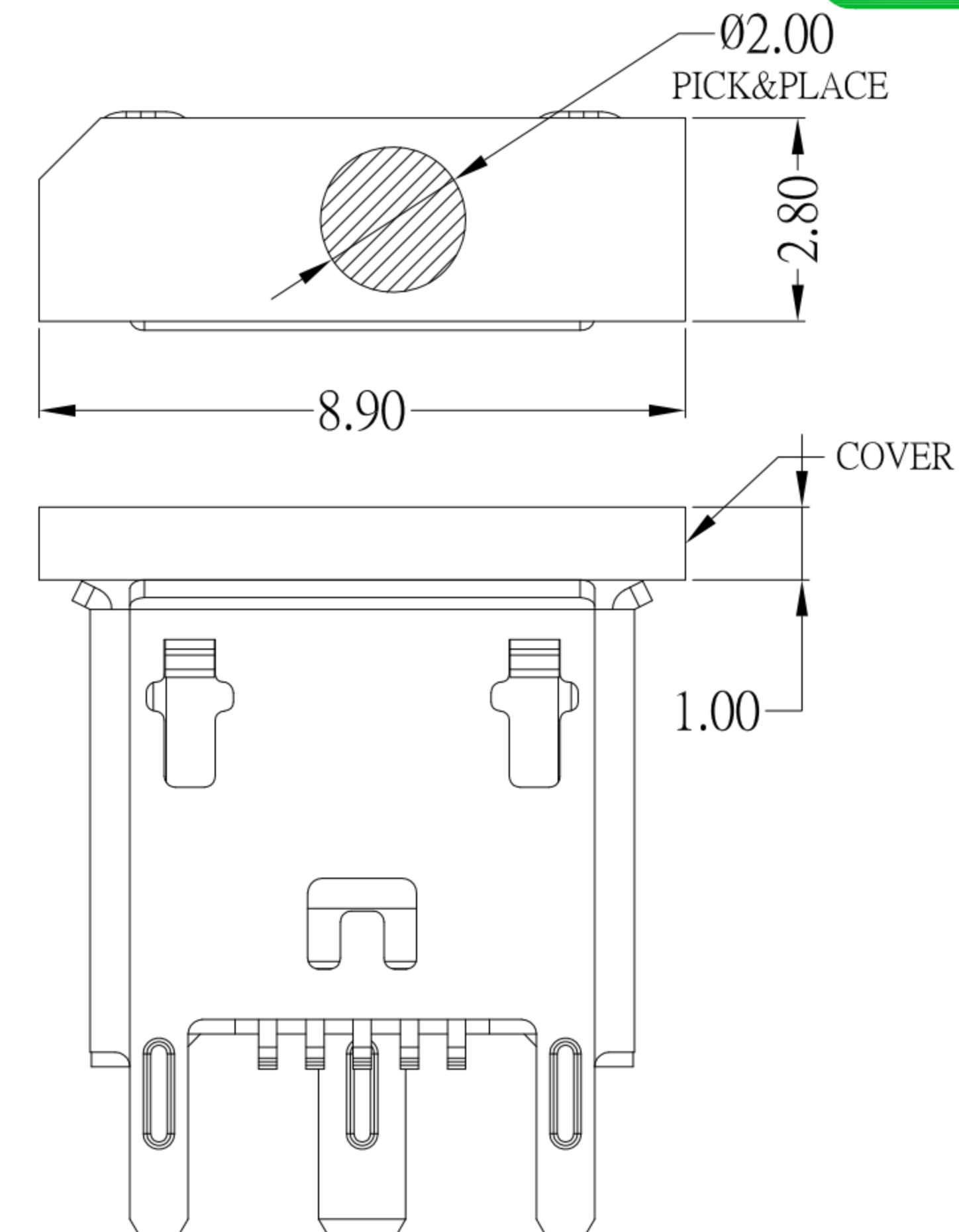
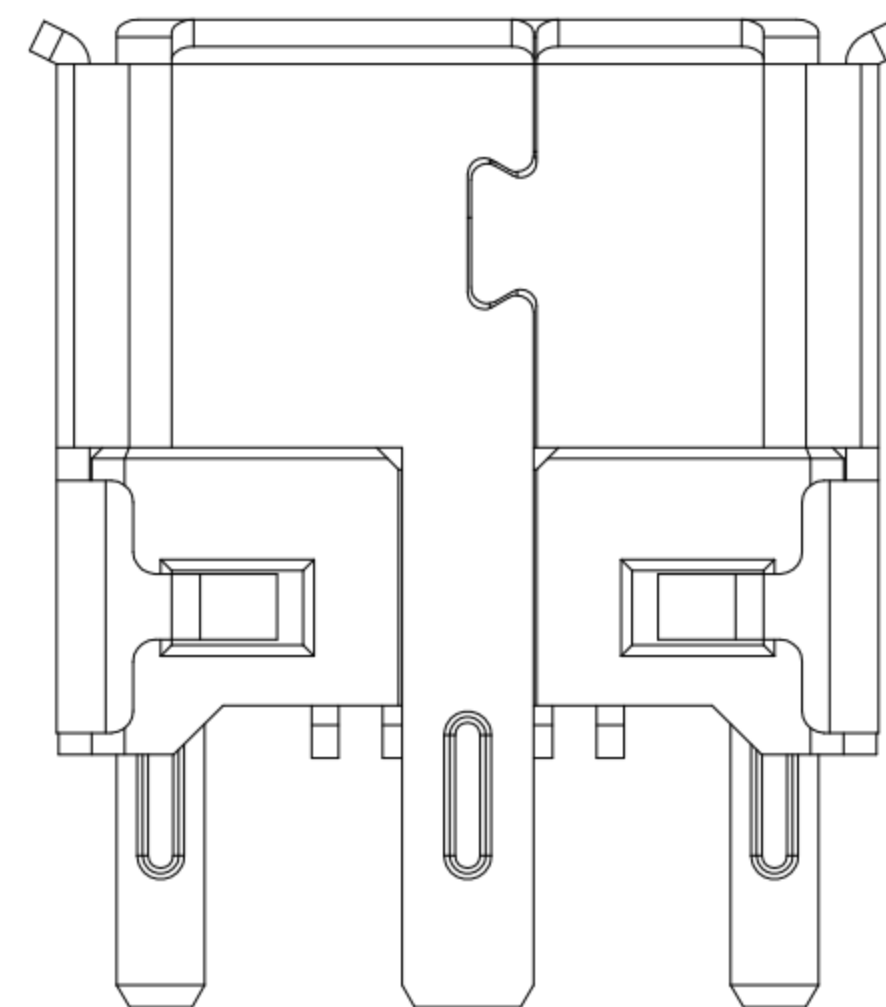
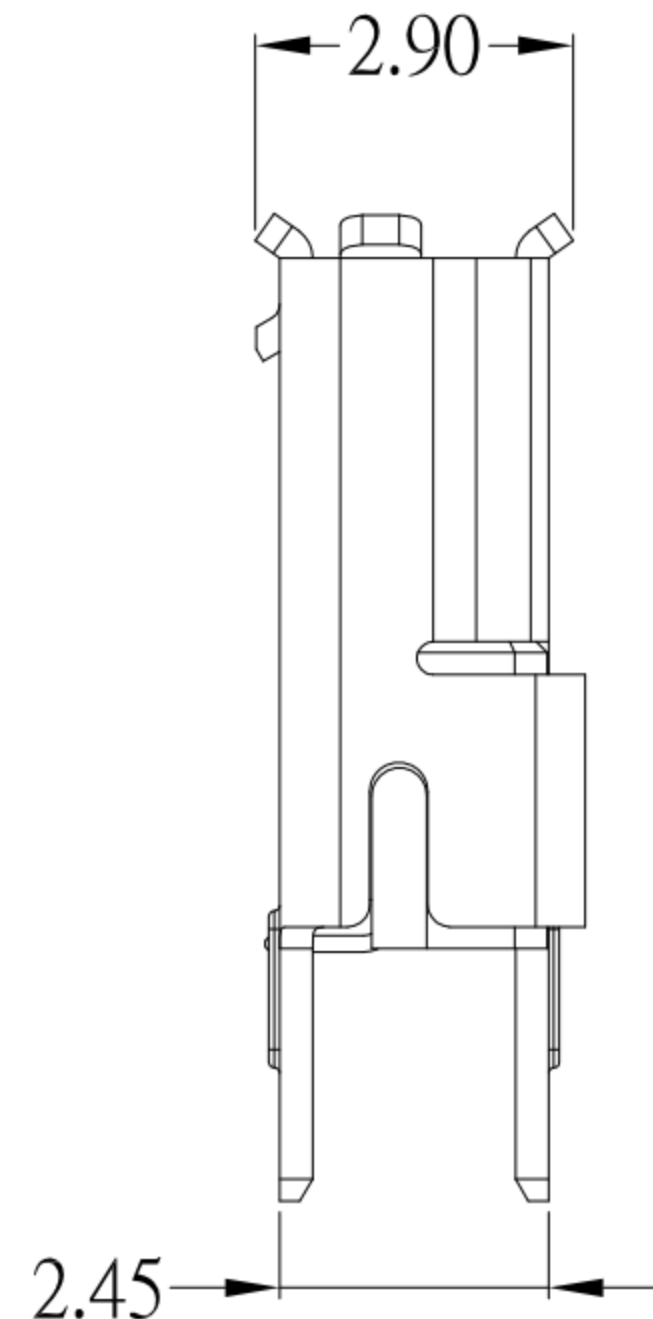
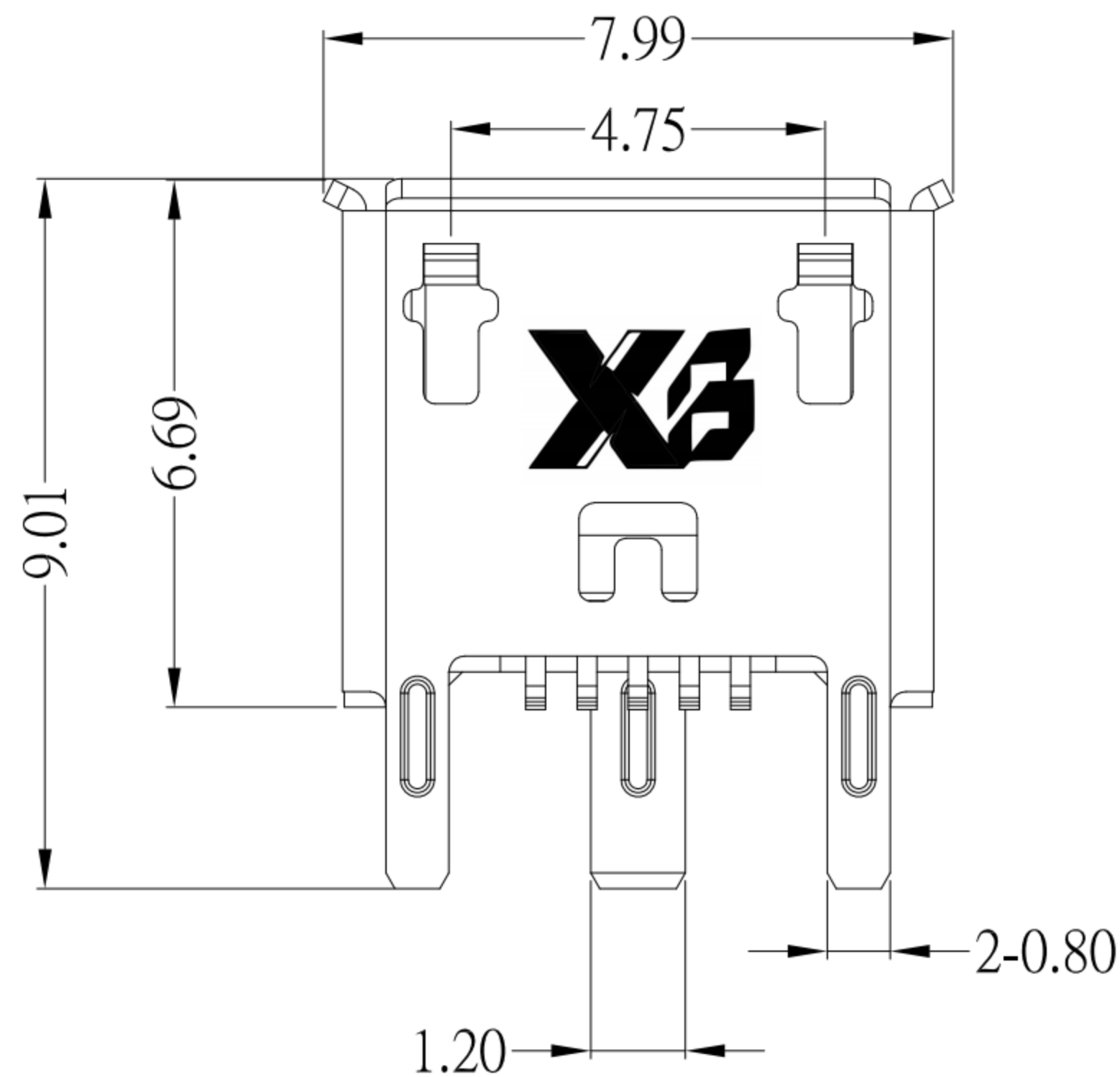
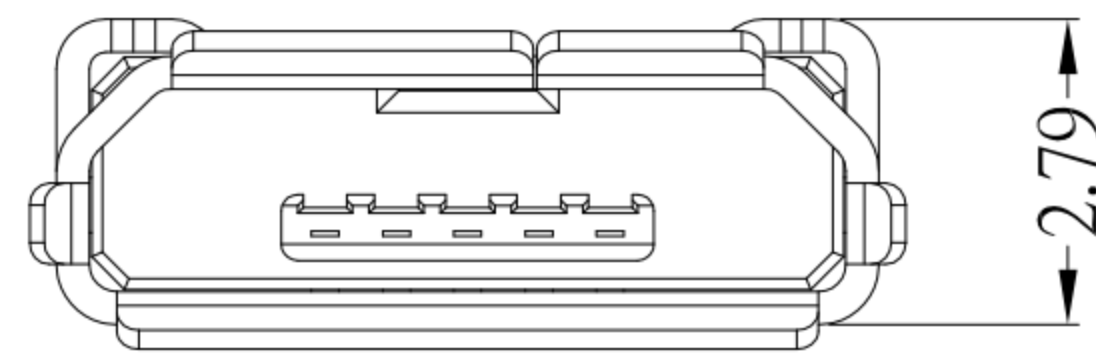




P.C.B LAYOUT MOUNTING PATTERN

NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

- 2.2 SHELL: TIN UNDER PLATED SURFACE LAYER

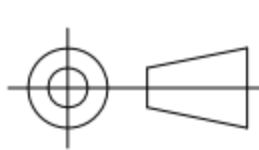
3.SPECIFICATION:

- 3.1 CURRENT RATING: 2.0 A MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 50 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C



TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 08/28/17
DATE: 08/28/17
DATE: 08/28/17

SHEET NO.	1 of 1	PART NO.	MRUSB-5B-VS4-S316	SIZE
TITLE	MODLE	DWG NO.	MRUSB-5B-VS4-S316	VER
MAT'L	FINISH	SCALE	1 : 1	R2